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U.S. PATENT DOCUMENTS							
Examiner Initial		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
FOREIGN PATENT DOCUMENTS							
		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION
						YES NO	
OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)							
hy			Y.T. Cheng et al.; Vacuum Packaging Technology Using Localized Aluminum/Silicon-to-Glass Bonding; Center for Wireless Integrated Microsystems; University of Michigan; IEEE 0-7803-5998-4/01; 2001 (pages 18-21).				
			C. Yu et al.; Antireflection Coatings for Advanced Semiconductor Device Metallization Using Laser Reflow and Chemical Mechanical Planarization; Appl. Phys. Lett. 59 (16), 10/14/91 (pages 1978-1980).				
hy			Ruichen Liu, K. P. Cheung, and W. Y.-C. Lai; A Study of Pulsed Laser Planarization of Aluminum for VLSI Metallization; AT&T Bell Laboratories; 1989 VMIC Conference 6/12-13/89; 1989 IEEE TH-0259-2/89/0000-0329 (pages 329-335).				
			B. Woratschek et al.; Improved Excimer Laser Planarization of AISI with Addition of Ti or Cu; Siemens AG; 1989 VMIC Conference 6/12-13/89; 1989 IEEE TH-0259-2/89/0000-0309 (pages 309-314)				
Examiner <i>David Huang</i>					DATE CONSIDERED <i>07/2005</i>		
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